

## HRW0202B

### Silicon Schottky Barrier Diode for Rectifying

REJ03G0153-0200Z  
(Previous: ADE-208-345A)  
Rev.2.00  
Dec.15.2003

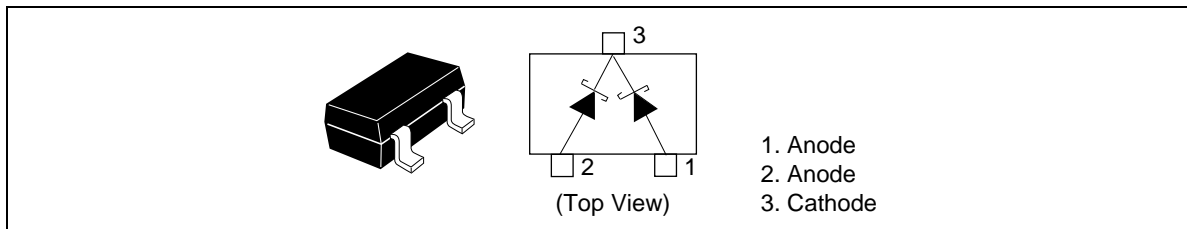
#### Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

#### Ordering Information

Type No.	Laser Mark	Package Code
HRW0202B	S18	MPAK

#### Pin Arrangement



### Absolute Maximum Ratings <sup>\*1</sup>

(T<sub>a</sub> = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V <sub>RMM</sub> <sup>*2</sup>	20	V
Average rectified current	I <sub>O</sub> <sup>*2</sup>	200	mA
Non-Repetitive peak forward surge current	I <sub>FSM</sub> <sup>*3</sup>	3	A
Junction temperature	T <sub>J</sub>	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

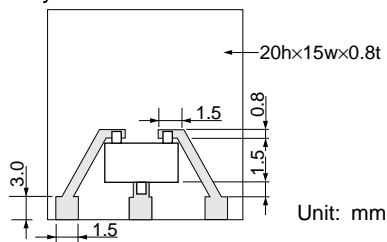
- Notes: 1. Two device total  
 2. See from Fig.4 to Fig.7  
 3. 10ms sine wave 1 pulse

### Electrical Characteristics <sup>\*1</sup>

(T<sub>a</sub> = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V <sub>F</sub>	—	—	0.42	V	I <sub>F</sub> = 100 mA
Reverse current	I <sub>R</sub>	—	—	10	μA	V <sub>R</sub> = 20 V
Thermal resistance	R <sub>th(j-a)</sub>	—	400	—	°C/W	Polyimide board <sup>*2</sup>

- Notes: 1. Per one device  
 2. Polyimide board



Main Characteristic

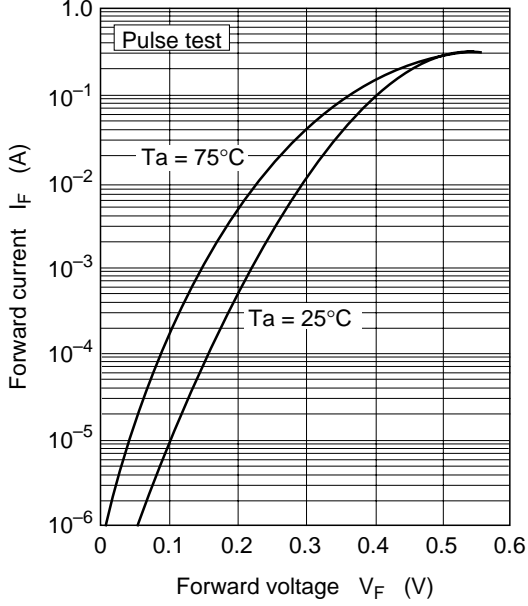


Fig.1 Forward current vs. Forward voltage

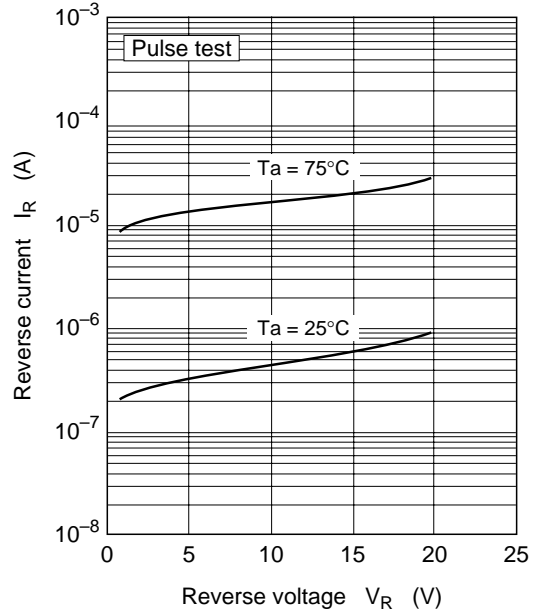


Fig.2 Reverse current vs. Reverse voltage

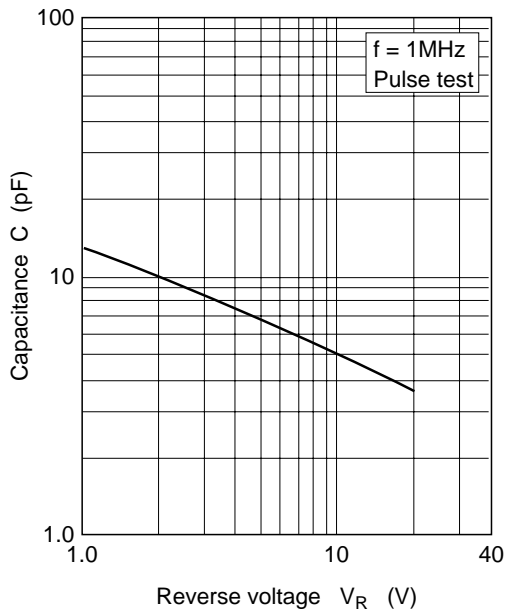


Fig.3. Capacitance vs. Reverse voltage

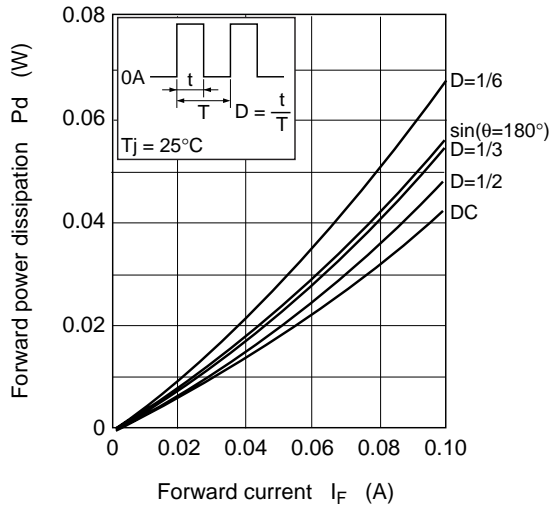


Fig.4 Forward power dissipation vs. Forward current

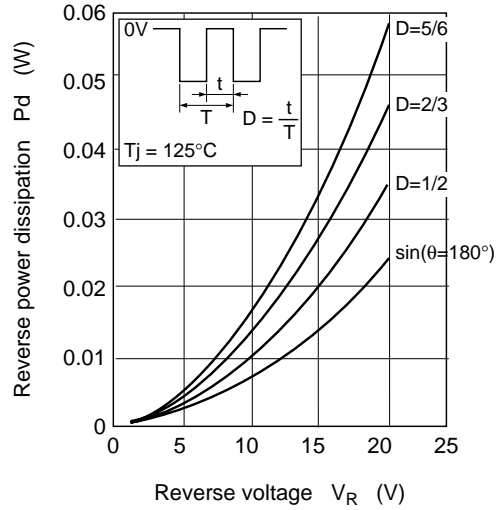


Fig.5 Reverse power dissipation vs. Reverse voltage

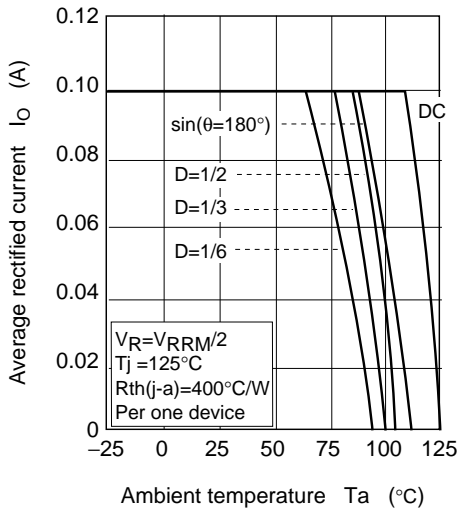


Fig.6 Average rectified current vs. Ambient temperature

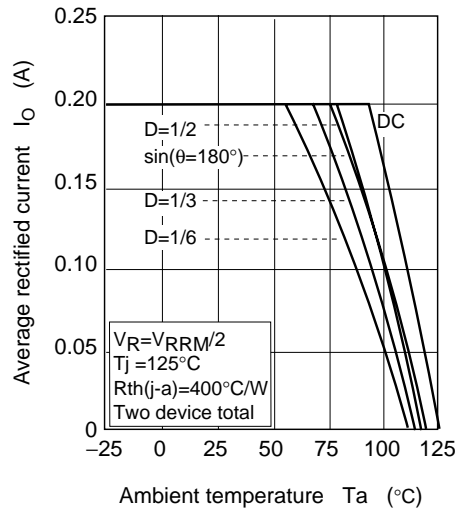
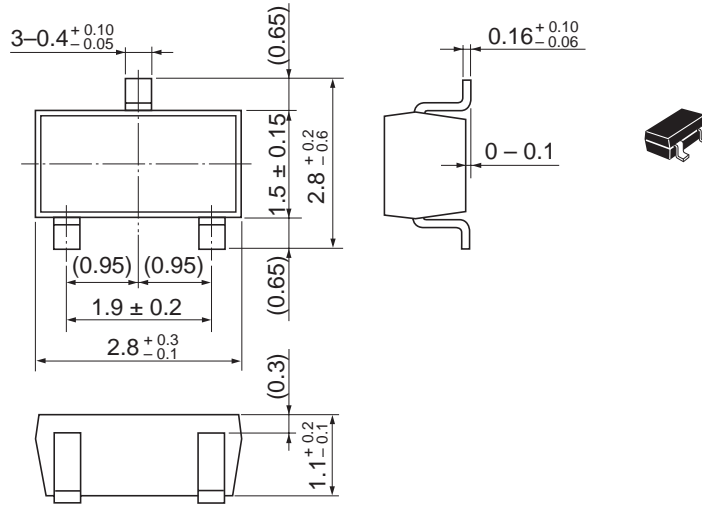


Fig.7 Average rectified current vs. Ambient temperature

Package Dimensions

As of January, 2003  
Unit: mm



Package Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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